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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Serial No. 09/546,174

Application of: Chih-Chien Liu, Ta-Shan Tseng, W. B.

Shieh, J. Y. Wu, Water Lur and Shih-Wei Sun

Filed: April 11, 2000

Art Unit: 1711

Examiner: Sergent, Rabon A.

Attomey Docket No. UMC-96-279 CON

For: HIGH DENSITY PLASMA CHEMICAL VAPOR

DEPOSITION PROCESS

Confirmation No.: 4793

Customer No.: 25235

AMENDMENT AND RESPONSE PURSUANT TO FINAL OFFICE ACTION DATED AUGUST 25, 2005

MAIL STOP AF
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir.

In response to the final office communication mailed August 25, 2005, please amend the above-identified application as follows:

Amendments to the Claims are reflected in the listing of claims which begins on page 2 of this paper.

Remarks/Arguments begin on page 11 of this paper.

NCS - 818460018 - 77125 42